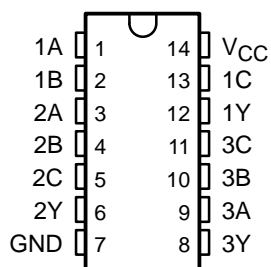


SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11 TRIPLE 3-INPUT POSITIVE-AND GATES

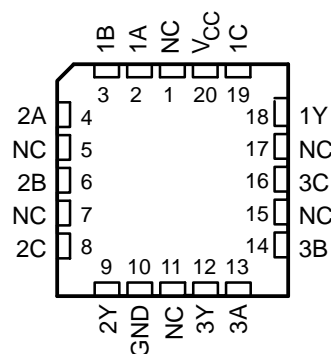
SDAS009D – MARCH 1984 – REVISED NOVEMBER 2002

- 4.5-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 5.5 ns at 5 V

SN54ALS11A, ... J OR W PACKAGE
SN54AS11 ... J PACKAGE
SN74ALS11A, SN74AS11 ... D, N, OR NS PACKAGE
(TOP VIEW)



SN54ALS11A, SN54AS11 ... FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

These devices contain three independent 3-input positive-AND gates. They perform the Boolean functions $Y = A \cdot B \cdot C$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	PDIP – N	Tube	SN74ALS11AN	SN74ALS11AN	
			SN74AS11N	SN74AS11N	
	SOIC – D	Tube	SN74ALS11AD	ALS11A	
			Tape and reel		SN74ALS11ADR
			Tube	SN74AS11D	AS11
				Tape and reel	
SOP – NS	Tape and reel	SN74ALS11ANSR	ALS11A		
		SN74AS11NSR	74AS11		
–55°C to 125°C	CDIP – J	Tube	SNJ54ALS11AJ	SNJ54ALS11AJ	
			SNJ54AS11J	SNJ54AS11J	
	CFP – W	Tube	SNJ54ALS11AW	SNJ54ALS11AW	
			SNJ54ALS11AFK	SNJ54ALS11AFK	
LCCC – FK	Tube	SNJ54ALS11AFK	SNJ54ALS11AFK		
		SNJ54AS11FK	SNJ54AS11FK		

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11

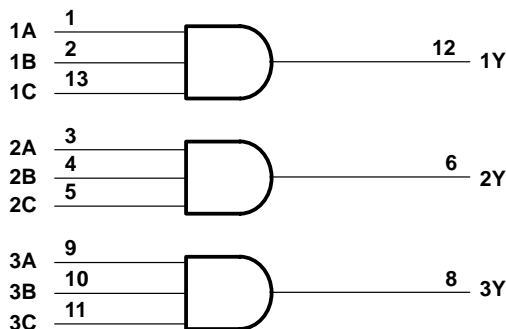
TRIPLE 3-INPUT POSITIVE-AND GATES

SDAS009D – MARCH 1984 – REVISED NOVEMBER 2002

FUNCTION TABLE
(each gate)

INPUTS			OUTPUT
A	B	C	Y
H	H	H	H
L	X	X	L
X	L	X	L
X	X	L	L

logic diagram, each gate (positive logic)



Pin numbers shown are for the D, J, N, NS, and W packages.

absolute maximum ratings over operating free-air temperature range (SN54ALS11A, SN74ALS11A) (unless otherwise noted)[†]

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Package thermal impedance, θ_{JA} (see Note 1): D package	86°C/W
N package	80°C/W
NS package	76°C/W
Storage temperature range	-65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

	SN54ALS11A			SN74ALS11A			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC} Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH} High-level input voltage	2			2			V
V_{IL} Low-level input voltage			0.8 [‡]			0.8	V
			0.7 [§]				
I_{OH} High-level output current			-0.4			-0.4	mA
I_{OL} Low-level output current			4			8	mA
T_A Operating free-air temperature	-55		125	0		70	°C

[‡] Applies over temperature range -55°C to 70°C

[§] Applies over temperature range 70°C to 125°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11 TRIPLE 3-INPUT POSITIVE-AND GATES

SDAS009D – MARCH 1984 – REVISED NOVEMBER 2002

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS11A		SN74ALS11A		UNIT			
		MIN	TYP†	MAX	MIN		TYP†	MAX	
V_{IK}	$V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$			-1.5		-1.5	V		
V_{OH}	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$, $I_{OH} = -0.4\text{ mA}$			$V_{CC} - 2$		$V_{CC} - 2$	V		
V_{OL}	$V_{CC} = 4.5\text{ V}$			0.25	0.4	0.25	0.4	V	
						0.35	0.5		
I_I	$V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$				0.1		0.1	mA	
I_{IH}	$V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$				20		20	μA	
I_{IL}	$V_{CC} = 5.5\text{ V}$, $V_I = 0.4\text{ V}$				-0.1		-0.1	mA	
$I_{O\ddagger}$	$V_{CC} = 5.5\text{ V}$, $V_O = 2.25\text{ V}$	-20		-112		-30		-112	mA
I_{CCH}	$V_{CC} = 5.5\text{ V}$, $V_I = 4.5\text{ V}$			1	1.8		1	1.8	mA
I_{CCL}	$V_{CC} = 5.5\text{ V}$, $V_I = 0$			1.6	3		1.6	3	mA

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V TO }5.5\text{ V}$, $C_L = 50\text{ PF}$, $R_L = 500\ \Omega$, $T_A = \text{MIN TO MAX}\S$				UNIT
			SN54ALS11A		SN74ALS11A		
			MIN	MAX	MIN	MAX	
t_{PLH}	A, B, or C	Y	2	14	2	13	ns
t_{PHL}			2	12.5	2	10	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (SN54AS11, SN74AS11) (unless otherwise noted)¶

Supply voltage, V_{CC}	7 V
Input voltage, V_I	7 V
Package thermal impedance, θ_{JA} (see Note 1):	
D package	86°C/W
N package	80°C/W
NS package	76°C/W
Storage temperature range	-65°C to 150°C

¶ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11 TRIPLE 3-INPUT POSITIVE-AND GATES

SDAS009D – MARCH 1984 – REVISED NOVEMBER 2002

recommended operating conditions (see Note 2)

		SN54AS11			SN74AS11			UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX		
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
V _{IH}	High-level input voltage	2			2			V	
V _{IL}	Low-level input voltage	0.8			0.8			V	
I _{OH}	High-level output current	-2			-2			mA	
I _{OL}	Low-level output current	20			20			mA	
T _A	Operating free-air temperature	-55			0			70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54AS11			SN74AS11			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA	-1.2			-1.2			V
V _{OH}	V _{CC} = 4.5 V to 5.5 V, I _{OH} = -2 mA	V _{CC} -2			V _{CC} -2			V
V _{OL}	V _{CC} = 4.5 V, I _{OL} = 20 mA	0.35 0.5			0.35 0.5			V
I _I	V _{CC} = 5.5 V, V _I = 7 V	0.1			0.1			mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V	20			20			μA
I _{IL}	V _{CC} = 5.5 V, V _I = 0.4 V	-0.5			-0.5			mA
I _O ‡	V _{CC} = 5.5 V, V _O = 2.25 V	-30 -112			-30 -112			mA
I _{CCH}	V _{CC} = 5.5 V, V _I = 4.5 V	4.3 7			4.3 7			mA
I _{CCL}	V _{CC} = 5.5 V, V _I = 0	11.2 18			11.2 18			mA

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I_{OS}.

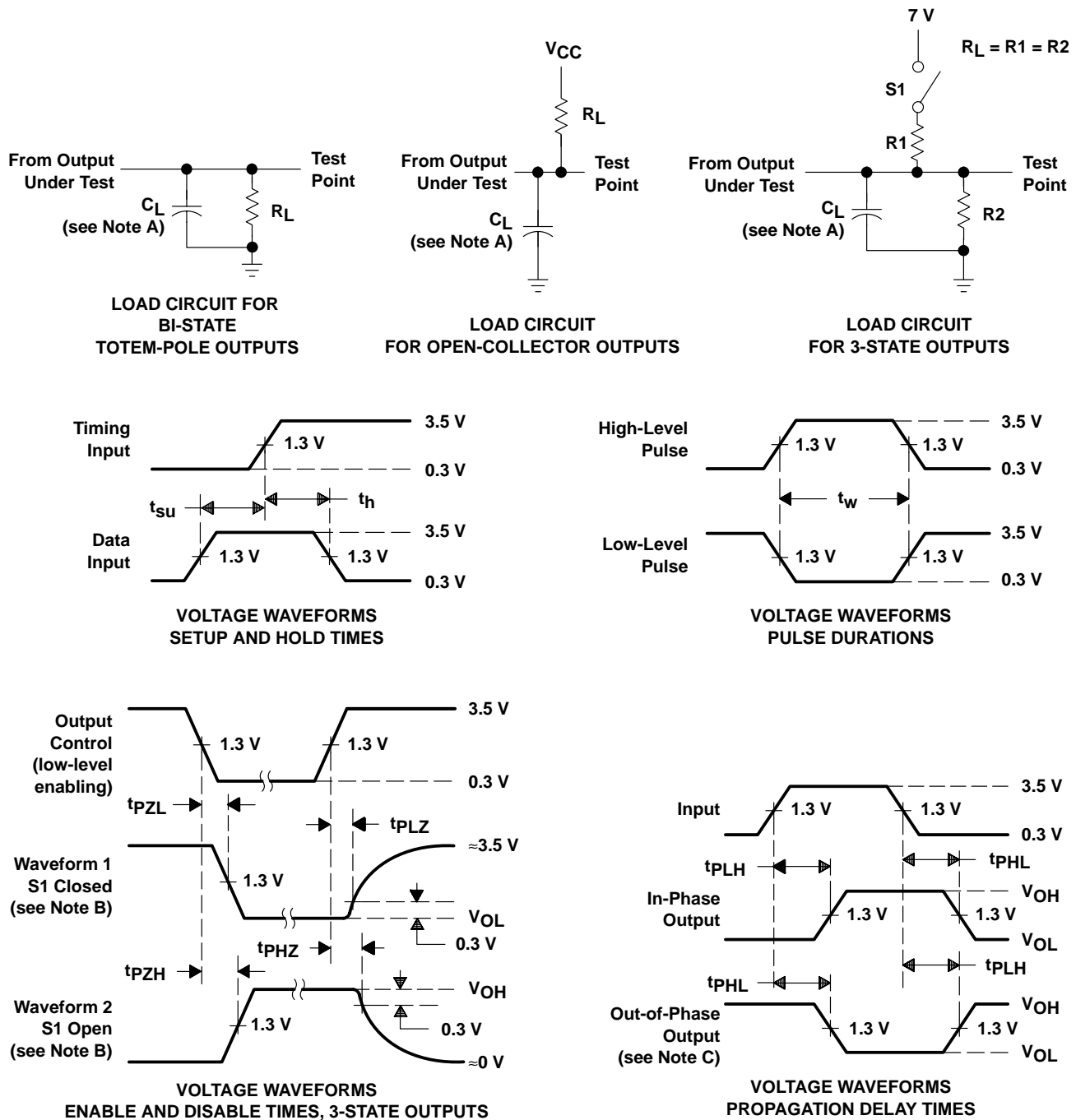
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V TO 5.5 V, C _L = 50 PF, R _L = 500 Ω, T _A = MIN TO MAX§				UNIT
			SN54AS11		SN74AS11		
			MIN	MAX	MIN	MAX	
t _{PLH}	A, B, or C	Y	1	6.5	1	6	ns
t _{PHL}			1	6.5	1	5.5	

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-86841012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-86841012A SNJ54ALS 11AFK
5962-8684101CA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8684101CA SNJ54ALS11AJ
5962-8684101DA	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8684101DA SNJ54ALS11AW
5962-9756101QCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9756101QC A SNJ54AS11J
JM38510/37402BCA	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510/ 37402BCA
SN54ALS11AJ	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54ALS11AJ
SN54AS11J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54AS11J
SN74ALS11AD	Obsolete	Production	SOIC (D) 14	-	-	Call TI	Call TI	0 to 70	ALS11A
SN74ALS11ADR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS11A
SN74ALS11AN	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU NIPDAU	N/A for Pkg Type	0 to 70	SN74ALS11AN
SN74ALS11ANSR	Active	Production	SOP (NS) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS11A
SN74AS11D	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS11
SN74AS11N	Active	Production	PDIP (N) 14	25 TUBE	Yes	NIPDAU NIPDAU	N/A for Pkg Type	0 to 70	SN74AS11N
SNJ54ALS11AFK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-86841012A SNJ54ALS 11AFK
SNJ54ALS11AJ	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8684101CA SNJ54ALS11AJ
SNJ54ALS11AW	Active	Production	CFP (W) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8684101DA SNJ54ALS11AW
SNJ54AS11J	Active	Production	CDIP (J) 14	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9756101QC A SNJ54AS11J

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11 :

● Catalog : [SN74ALS11A](#), [SN74AS11](#)

● Military : [SN54ALS11A](#), [SN54AS11](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS11ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS11ANSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS11ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN74ALS11ANSR	SOP	NS	14	2000	356.0	356.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-86841012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8684101DA	W	CFP	14	25	506.98	26.16	6220	NA
SN74ALS11AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74ALS11AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74AS11D	D	SOIC	14	50	506.6	8	3940	4.32
SN74AS11N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AS11N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54ALS11AFK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ALS11AW	W	CFP	14	25	506.98	26.16	6220	NA

D0014A



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F14

GENERIC PACKAGE VIEW

FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4229370VA\

J 14

GENERIC PACKAGE VIEW
CDIP - 5.08 mm max height
CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



4214771/A 05/2017

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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